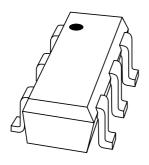
DISCRETE SEMICONDUCTORS

DATA SHEET



BAW101SHigh voltage double diode

Product data sheet

2003 May 13



High voltage double diode

BAW101S

FEATURES

- Small plastic SMD package
- High switching speed: max. 50 ns
- High continuous reverse voltage: 300 V
- Electrically insulated diodes.

APPLICATIONS

- · High voltage switching
- Automotive
- Communication.

DESCRIPTION

The BAW101S is a high-speed switching diode array with two separate dice, fabricated in planar technology and encapsulated in a small SOT363 plastic SMD package.

MARKING

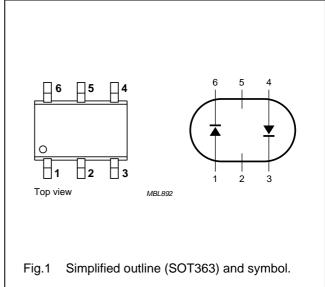
TYPE NUMBER	MARKING CODE(1)
BAW101S	K2*

Note

- 1. * = p: Made in Hong Kong.
 - * = t: Made in Malaysia.
 - * = W: Made in China.

PINNING

PIN	DESCRIPTION	
1	anode 1	
2	n.c.	
3	cathode 2	
4	anode 2	
5	n.c.	
6	cathode 1	



2003 May 13 2

High voltage double diode

BAW101S

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT	
Per diode	Per diode					
V_R	continuous reverse voltage		_	300	V	
		series connection	_	600	V	
V_{RRM}	repetitive peak reverse voltage		_	300	V	
		series connection	_	600	V	
I _F	continuous forward current	single diode loaded; note 1; see Fig.2	_	250	mA	
		double diode loaded; note 1; see Fig.2	_	140	mA	
I _{FRM}	repetitive peak forward current		_	625	mA	
I _{FSM}	non-repetitive peak forward current	square wave; $T_j = 25$ °C prior to surge; $t = 1 \mu s$	_	4.5	А	
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	350	mW	
T _{stg}	storage temperature		-65	+150	°C	
Tj	junction temperature		_	150	°C	
T _{amb}	operating ambient temperature		-65	+150	°C	

Note

ELECTRICAL CHARACTERISTICS

 $T_j = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER CONDITIONS		MIN.	MAX.	UNIT
Per diode					
V _{BR(R)}	reverse breakdown voltage	I _R = 100 μA	300	_	V
V _F	forward voltage	I _F = 100 mA; note 1	_	1.1	V
I _R	reverse current	V _R = 250 V	_	150	nA
		V _R = 250 V; T _{amb} = 150 °C	_	50	μΑ
t _{rr}	reverse recovery time	when switched from I_F = 30 mA to I_R = 30 mA; R_L = 100 Ω ; measured at I_R = 3 mA		50	ns
C _d	diode capacitance	V _R = 0 V; f = 1 MHz	_	2	pF

Note

1. Pulse test: pulse width = 300 μ s; δ = 0.02.

2003 May 13 3

^{1.} Device mounted on an FR4 printed-circuit board, cathode-lead mounting pad = 1 cm².

High voltage double diode

BAW101S

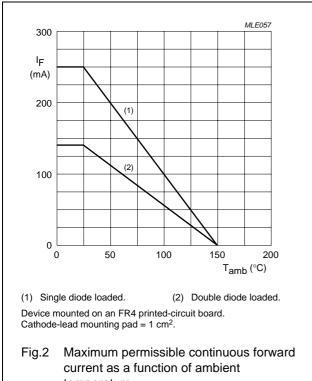
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	note 1	255	K/W
R _{th j-a}	thermal resistance from junction to ambient	note 2	357	K/W

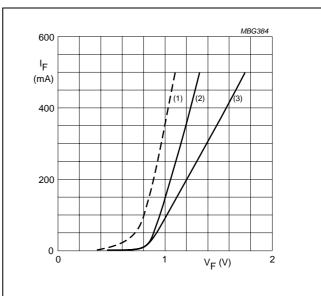
Notes

- 1. One or more diodes loaded.
- 2. Device mounted on an FR4 printed-circuit board, cathode-lead mounting pad = 1 cm².

GRAPHICAL DATA



temperature.



- (1) $T_j = 150$ °C; typical values.
- (2) $T_j = 25$ °C; typical values.

4

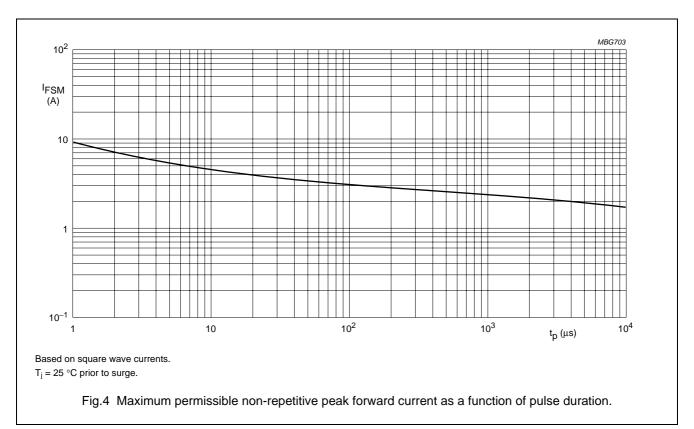
(3) $T_j = 25$ °C; maximum values.

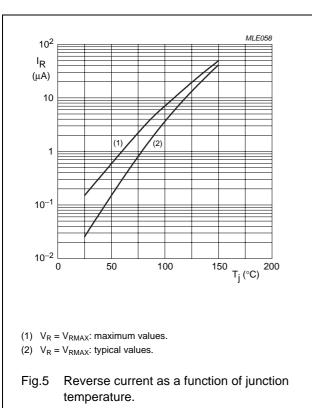
Fig.3 Forward current as a function of forward voltage.

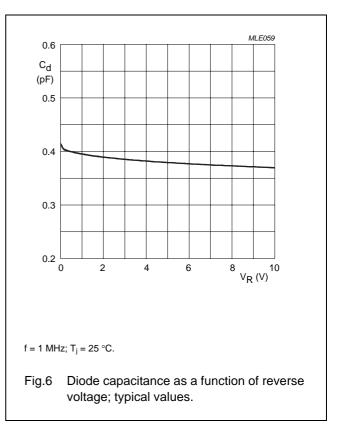
2003 May 13

High voltage double diode

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High voltage double diode

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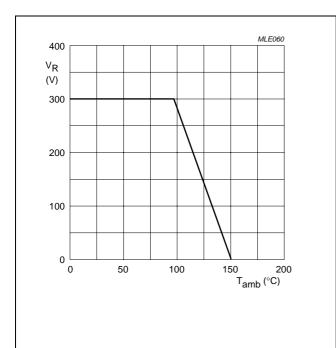


Fig.7 Maximum permissible continuous reverse voltage as a function of ambient temperature.

2003 May 13 6

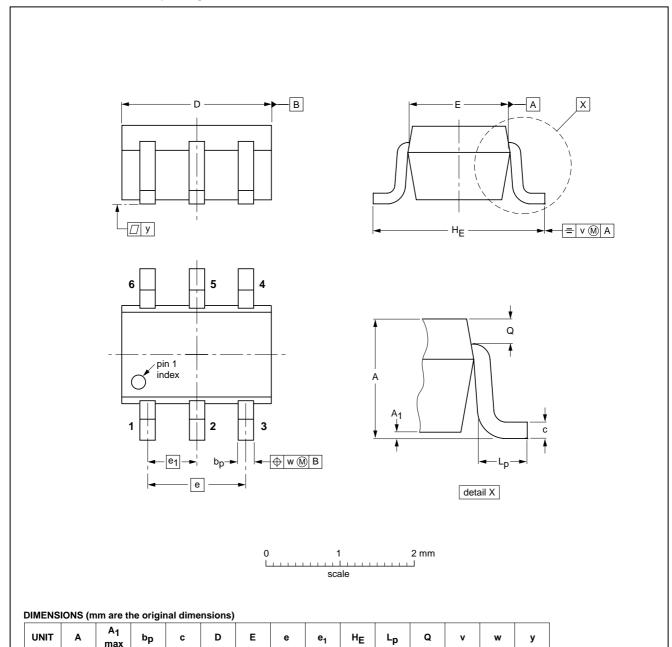
High voltage double diode

BAW101S

PACKAGE OUTLINE

Plastic surface mounted package; 6 leads

SOT363



OUTLINE	REFERENCES			EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT363			SC-88			97-02-28

0.65

0.45 0.15 0.25 0.15

0.2

0.1

2003 May 13 7

0.25 0.10

0.30

0.20

1.1 0.8

0.1

mm

2.2 1.8 1.35 1.15

1.3

High voltage double diode

BAW101S

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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2003 May 13 8

NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors. No changes were made to the content, except for the legal definitions and disclaimers.

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Printed in The Netherlands 613514/01/pp9 Date of release: 2003 May 13 Document order number: 9397 750 11148



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